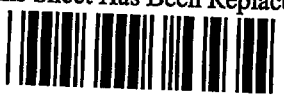
ABSTRACT OF THE DISCLOSURE

A heat-resistant adhesive is provided for use in an adhesive member for the fabrication of a semiconductor package by bonding a semiconductor chip to a lead frame with the adhesive member and sealing at least the semiconductor chip and a bonded part between the semiconductor chip and the lead frame with a sealant. The adhesive has a coming-out length of not more than 2 mm and a water absorption rate of not more than 3 wt.%. Preferably, the adhesive has a glass transition point of at least 200°C.

This Sheet Has Been Replaced



THIS SHEET HAS BEEN REPLACED